

NEC's WIDE BAND SPDT SWITCH UPD5710TK

FEATURES

• SUPPLY VOLTAGE:

 $V_{DD} = 1.8 \text{ to } 3.3 \text{ V } (3.0 \text{ V TYP.})$

• SWITCH CONTROL VOLTAGE:

 $V_{cont}(H) = 1.8 \text{ to } 3.3 \text{ V } (3.0 \text{ V TYP.})$ $V_{cont(L)} = -0.2 \text{ to } +0.2 \text{ V (0 V TYP.)}$

LOW INSERTION LOSS:

Lins1 = 0.6 dB TYP. @ f = DC to 1.0 GHz $L_{ins2} = 0.8 \text{ dB TYP.} @ f = 1.0 \text{ to } 2.0 \text{ GHz}$ $L_{ins3} = 0.95 \text{ dB TYP.} @ f = 2.0 \text{ to } 2.5 \text{ GHz}$

• HIGH ISOLATION:

ISL1 = 32.5 dB TYP. @ f = DC to 1.0 GHz ISL2 = 25 dB TYP. @ f = 1.0 to 2.0 GHz ISL3 = 22.5 dB TYP. @ f = 2.0 to 2.5 GHz

POWER HANDLING:

 $P_{in (0.1 dB)} = +17.0 dBm TYP. @ f = 1.0GHz, V_{DD} = 3.0 V$ $P_{in} (1 dB) = +21.0 dBm TYP. @ f = 1.0 GHz. VDD = 3.0 V$

HIGH-DENSITY SURFACE MOUNTING:

6-pin minimold package (1.5 \times 1.1 \times 0.55 mm)

LEAD FREE

DESCRIPTION

NEC's UPD5710TK is a wide-band CMOS MMIC SPDT (Single Pole Double Throw) switch for mobile communications, instrumentation, short range wireless, and general-purpose RF switching applications.

This device can operate from DC to 2.5GHz with low insertion loss and high isolation.

The UPD5710TK is housed in a 6-pin minimold (1511) package, suitable for high-density surface mounting.

APPLICATIONS

- **MOBILE COMMUNICATIONS**
- **SET TOP BOXES**
- SHORT RANGE WIRELESS
- INSTRUMENTATION

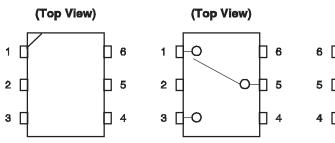
ORDERING INFORMATION

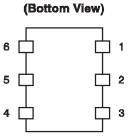
PART NUMBER	PACKAGE	MARKING	SUPPLYING FORM
μPD5710TK-E2-A	6-pinlead-less minimold (1511)	C3L	Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 5 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: UPD5710TK

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM





PIN NO.	PIN NAME		
1	OUTPUT1		
2	GND		
3	OUTPUT2		
4	V _{cont2}		
5	INPUT		
6	V _{cont1}		

TRUTH TABLE

Vcont	INPUT-OUTPUT1	INPUT-OUTPUT2
Low	OFF	ON
High	ON	OFF

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Supply Voltage	V _{DD}	+4.6	V
Switch Control Voltage	Vcont	+4.6	V
Continuous Current	Idc	60	mA
Input Power	Pin	+27	dBm
Operating Ambient Temperature	TA	-45 to +85	°C
Storage Temperature	T _{stg}	-65 to +150	°C

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V _{DD}	+1.8	+2.8	+3.3	V
Switch Control Voltage (H)	Vcont (H)	+1.8	+2.8	+3.3	V
Switch Control Voltage (L)	Vcont (L)	-0.2	0	+0.2	V

Notes 1. $|V_{cont(H)} - V_{cont(L)}| \le 0.1 \text{ V}$

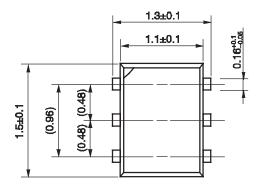
ELECTRICAL CHARACTERISTICS (TA = +25°C, VDD = 2.8V, Vcont(H) = 3.0 V, Vcont(L) = 0 V, unless otherwise specified)

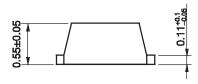
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Insertion Loss 1	Lins1	f = DC to 1.0 GHz	-	0.6	0.8	dB
Insertion Loss 2	Lins2	f = 1.0 to 2.0 GHz	_	0.8	1.0	dB
Insertion Loss 3	Lins3	f = 2.0 to 2.5 GHz	-	0.95	1.2	dB
Isolation 1	ISL1	f = DC to 1.0 GHz	30	32.5	-	dB
Isolation 2	ISL2	f = 1.0 to 2.0 GHz	22	25	-	dB
Isolation 3	ISL3	f = 2.0 to 2.5 GHz	-	22.5	-	dB
Input Return Loss	RLin	f = DC to 2.5 GHz	15	20	-	dB
Output Return Loss	RLout	f = DC to 2.5 GHz	15	20	-	dB
0.1 dB Loss Compression Input Power Note	Pin (0.1 dB)	f = 1.0 GHz	+13.5	+17.0	-	dBm
1 dB Loss Compression Input Power Note	Pin (1 dB)	f = 1.0 GHz	_	+21.0	-	dBm
Intermodulation Intercept Point	IIP ₃	2 tone, 1.000/1.001GHz, 1 MHz spacing	_	+33	-	dBm
Supply Voltage	IDD	No RF	-	0.01	1.0	μΑ
Switch Control Current	Icont	No RF	-	0.01	1.0	μΑ
Switch Control Speed	tsw		_	30	500	ns

Notes . $P_{in (0.1 dB)}$ or $P_{in (1 dB)}$ are the measured input power level when the insertion loss increases 0.1 dB more or 1dB than that of linear range.

PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511) (UNIT:mm)





Remark (): Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature	: 260°C or below : 10 seconds or less	IR260
	Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	
VPS	Peak temperature (package surface temperature) Time at temperature of 200°C or higher Preheating time at 120 to 150°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 215°C or below : 25 to 40 seconds : 30 to 60 seconds : 3 times : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

